



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
 [List multiple models if applicable.]

HP S2032a LCD Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	2
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 SCREW DRIVER(PHILLIPS HEAD)	#2
Description #2	
Description #3	
Description #4	
Description #5	

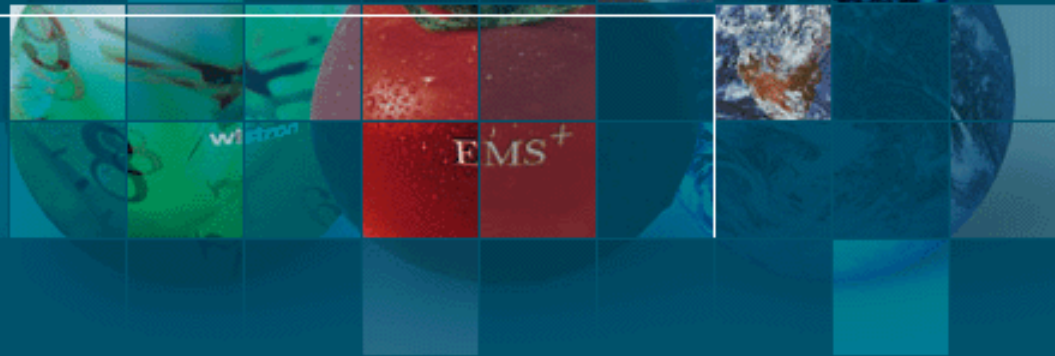
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. External Electric Cables Dissecting Process
2. Remove Stand Base From Display Head
3. Remove Rear Cover From Display Head
4. Remove Front Cover From Display Head
5. Remove Key Board Off From Front Cover
6. Take Screw(x9)Off From Chassis Cover
7. Remove Interface BD and Power BD From Chassis
8. Explode Stand Base
9. Take Screw(x3) Off From P.C.B
10. LCD PANEL EXPLODE
11. Electrolytic Capacitors Over 25mm High& Diameter Dissecting Process
12. Electrolytic Capacitors Process Drawing

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

HP S2032a Disassembly Process



Jan-19-2010
wistron

External Electric Cables Dissecting Process



1.Remove Cable From Display Head.

VGA Cable

Power Cord



2.Dissecting To Complete.

Remove Stand Base From Display Head



1. Take screw(x3) off from display head



2. Remove Stand Base From Display Head.

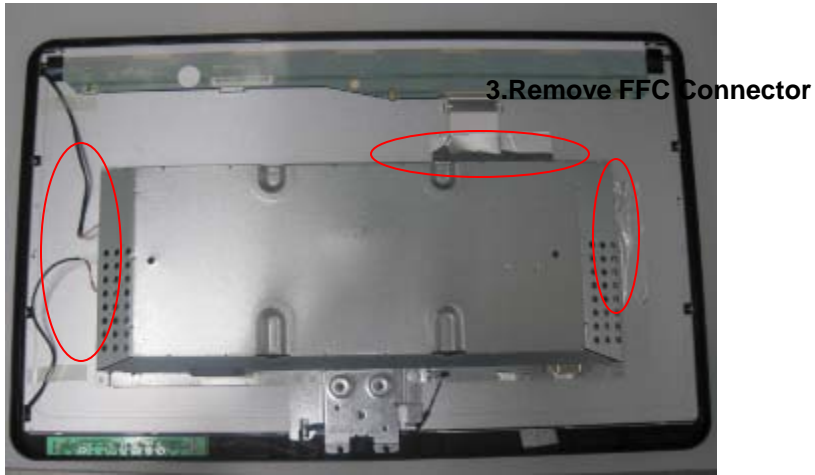
Remove Rear Cover From Display Head



1. Take screw(x1) off from display head



Remove Front Cover From Display Head



1.Remove light pipe Connector

2.Remove two pieces of Al foil

4.Remove key BD Connector from Interface BD

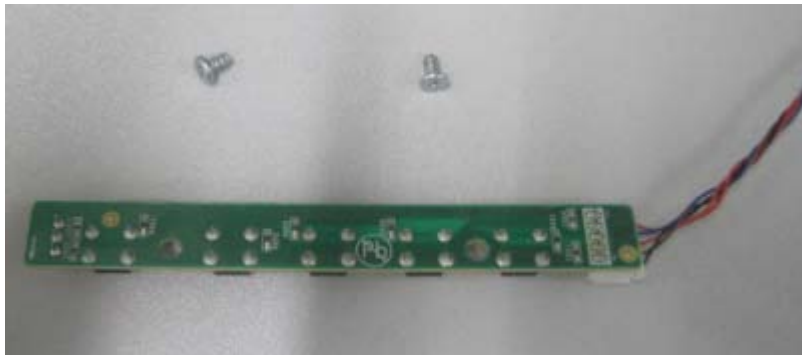


5. Remove Front Cover.

Remove Key Board Off From Front Cover

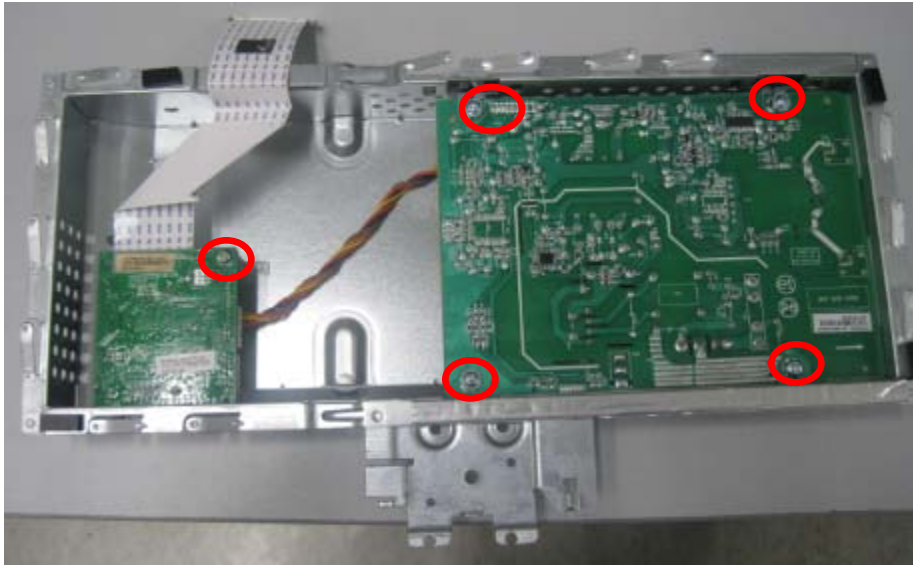


1. Take Screw(x2) Off From Front Cover



2. Remove key board from FC

Take Screw(x9) Off From Chassis Cover

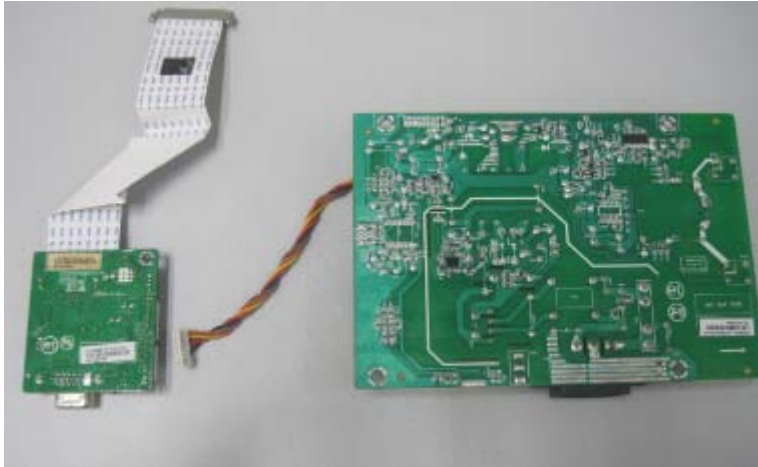


1. Take screw (X5) off from Interface BD and Power BD

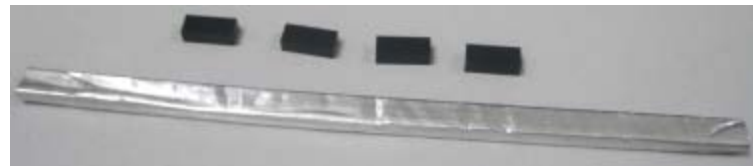


2. Take screw (X4) off from Interface BD and Power BD

Remove Interface BD and Power BD From Chassis Cover



1.Remove interface BD and power BD from chassis cover



2.Remove rubber and sponge from chassis cover

Explode Stand Base



1. Press hook and move base



2. Press release button and move stand top

Take Screw(x3) Off From Hinge



1. Take screw(x3) off from hinge

LCD PANEL EXPLODE

M200O1-L07 Recommended Disassembly Sequence



1. Remove 3 pcs screws and the pcb protector film from the moduel.



2. Release the hooks around the module for remove the front metal frame



3. Take off panel assembly.



4. Release lamp wire from housing and remove tape.



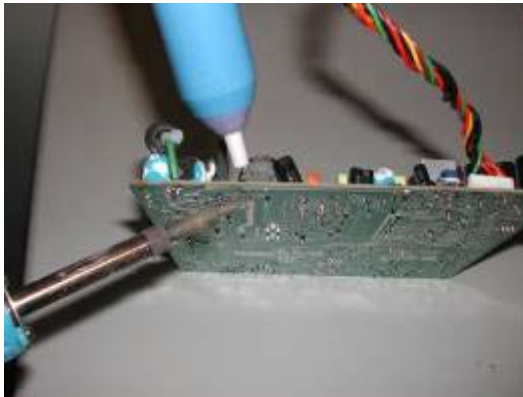
LCD PANEL EXPLODE

5. Remove plastic hosing.

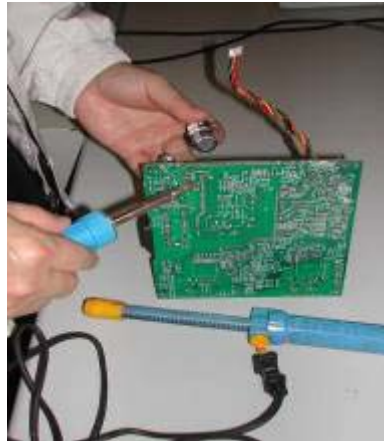


6. Remove LGP, lamps and films.

Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process



1.Heats Up, Dissolved Tin Lead.



2.Takes Down The Capacitor.



3.Dissecting To Complete.
(Next Page Have Description)

Electrolytic Capacitors Process Drawing



C805